#### MC74HCT20A

# Dual 4-Input NAND Gate with LSTTL-Compatible Inputs

### **High-Performance Silicon-Gate CMOS**

The MC74HCT20A is identical in pinout to the LS20. The device inputs are compatible with standard CMOS LSTTL outputs.

#### **Features**

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 4.5 V to 5.5 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- These are Pb-Free Devices

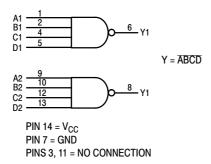


Figure 1. Logic Diagram



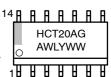
#### ON Semiconductor®

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#### MARKING DIAGRAMS



SOIC-14 D SUFFIX CASE 751A





TSSOP-14 DT SUFFIX CASE 948G

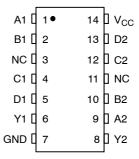


A = Assembly Location

WL, L = Wafer Lot
 YY, Y = Year
 WW, W = Work Week
 G or = Pb-Free Package

(Note: Microdot may be in either location)

#### **PIN ASSIGNMENT**



#### **FUNCTION TABLE**

|   | Inp | uts |   | Output |
|---|-----|-----|---|--------|
| Α | В   | С   | D | Υ      |
| L | Х   | Х   | Х | Н      |
| X | L   | Х   | Х | Н      |
| X | X   | L   | Х | Н      |
| X | Х   | Х   | L | Н      |
| Н | Н   | Н   | Н | L      |

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

#### MC74HCT20A

#### **MAXIMUM RATINGS**

| Symbol           | Parameter                                       | Value                        | Unit                         |    |
|------------------|---|------------------------------|------------------------------|----|
| V <sub>CC</sub>  | DC Supply Voltage (Referenced to GND)           |                              | -0.5 to +7.0                 | V  |
| V <sub>in</sub>  | DC Input Voltage (Referenced to GNI             | D)                           | -0.5 to V <sub>CC</sub> +0.5 | V  |
| V <sub>out</sub> | DC Output Voltage (Referenced to GND)           |                              | -0.5 to V <sub>CC</sub> +0.5 | V  |
| I <sub>in</sub>  | DC Input Current, per Pin                       |                              | ±20                          | mA |
| I <sub>out</sub> | DC Output Current, per Pin                      |                              | ±25                          | mA |
| I <sub>CC</sub>  | DC Supply Current, V <sub>CC</sub> and GND Pins |                              | ±50                          | mA |
| P <sub>D</sub>   | Power Dissipation in Still Air                  | SOIC Package<br>SSOP Package | 500<br>450                   | mW |
| T <sub>stg</sub> | Storage Temperature                             |                              | -65 to +150                  | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq$  ( $V_{in}$  or  $V_{out}$ )  $\leq$   $V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V<sub>CC</sub>). Unused outputs must be left open.

#### RECOMMENDED OPERATING CONDITIONS

| Symbol                             | Parameter  | Min         | Max             | Unit |
|------------------------------------|--|-------------|-----------------|------|
| V <sub>CC</sub>                    | DC Supply Voltage (Referenced to GND)                | 4.5         | 5.5             | V    |
| V <sub>in</sub> , V <sub>out</sub> | DC Input Voltage, Output Voltage (Referenced to GND) | 0           | V <sub>CC</sub> | V    |
| T <sub>A</sub>                     | Operating Temperature Range, All Package Types       | <b>- 55</b> | + 125           | °C   |
| t <sub>r</sub> , t <sub>f</sub>    | Input Rise/Fall Time (Figure 1)                      | 0           | 500             | ns   |

#### DC CHARACTERISTICS (Voltages Referenced to GND)

|                 |   |   | V <sub>CC</sub> | Guara          | nteed Lin  | nit        |      |
|-----------------|---|---|-----------------|----------------|------------|------------|------|
| Symbol          | Parameter   | Condition   | v               | -55 to 25°C    | ≤85°C      | ≤125°C     | Unit |
| V <sub>IH</sub> | Minimum High-Level Input Voltage                  | $V_{out} = 0.1V$<br>$ I_{out}  \le 20\mu A$   | 4.5<br>5.5      | 2.0<br>2.0     | 2.0<br>2.0 | 2.0<br>2.0 | V    |
| V <sub>IL</sub> | Maximum Low-Level Input Voltage                   | $V_{out} = V_{CC} - 0.1V$<br>$ I_{out}  \le 20\mu A$  | 4.5<br>5.5      | 0.8<br>0.8     | 0.8<br>0.8 | 0.8<br>0.8 | V    |
| V <sub>OH</sub> | Minimum High-Level Output<br>Voltage              | $V_{in} = V_{IL}$<br>$ I_{out}  \le 20\mu A$  | 4.5<br>5.5      | 4.4<br>5.4     | 4.4<br>5.4 | 4.4<br>5.4 | V    |
|                 |   | $V_{in} = V_{IL}$ $ I_{out}  \le 4.0 \text{mA}$   | 4.5             | 3.98           | 3.84       | 3.70       |      |
| V <sub>OL</sub> | Maximum Low-Level Output<br>Voltage               | $V_{in} = V_{IH}$<br>$ I_{out}  \le 20\mu A$  | 4.5<br>5.5      | 0.1<br>0.1     | 0.1<br>0.1 | 0.1<br>0.1 | V    |
|                 |   | $V_{in} = V_{IH}$ $ I_{out}  \le 4.0 \text{mA}$   | 4.5             | 0.26           | 0.33       | 0.40       |      |
| l <sub>in</sub> | Maximum Input Leakage Current                     | V <sub>in</sub> = V <sub>CC</sub> or GND  | 5.5             | ±0.1           | ±1.0       | ±1.0       | μΑ   |
| I <sub>CC</sub> | Maximum Quiescent Supply<br>Current (per Package) | $V_{in} = V_{CC}$ or GND $I_{out} = 0\mu A$   | 5.5             | 1              | 10         | 40         | μА   |
| $\Delta I_{CC}$ | Additional Quiescent Supply                       | V <sub>in</sub> = 2.4V, Any One Input<br>V <sub>in</sub> = V <sub>CC</sub> or GND, Other Inputs |                 | ≥ <b>-55°C</b> | 25 to      | 125°C      |      |
|                 | Odiferit  | $I_{out} = 0\mu A$  | 5.5             | 2.9            | 2          | .4         | mA   |

<sup>1.</sup> Information on typical parametric values can be found in Chapter 2 of the ON Semiconductor High-Speed CMOS Data Book (DL129/D).

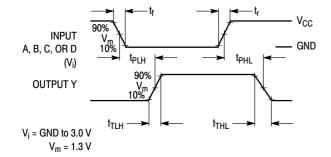
<sup>2.</sup> Total Supply Current =  $I_{CC} + \Sigma \Delta I_{CC}$ .

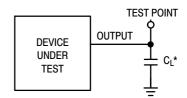
#### MC74HCT20A

#### AC ELECTRICAL CHARACTERISTICS ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6 \text{ ns}$ , $V_{CC} = 5.0 \text{ V}$ )

|  |   | Gu              | aranteed Li    | mit     |      |
|--|---|-----------------|----------------|---------|------|
| Symbol                                 | Parameter   | – 55 to<br>25°C | ≤ <b>85</b> °C | ≤ 125°C | Unit |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub> | Maximum Propagation Delay, Input A, B, or C to Output Y (Figures 2 and 3) | 28              | 35             | 42      | ns   |
| t <sub>TLH</sub> ,<br>t <sub>THL</sub> | Maximum Output Transition Time, Any Output (Figures 2 and 3)              | 15              | 19             | 22      | ns   |
| C <sub>in</sub>                        | Maximum Input Capacitance   | 10              | 10             | 10      | pF   |

|          |  | Typical @ 25°C, V <sub>CC</sub> = 5.0 V |    | ĺ |
|----------|--|---|----|---|
| $C_{PD}$ | Power Dissipation Capacitance (Per Gate) | 26                                      | pF |   |





\*Includes all probe and jig capacitance

Figure 3. Test Circuit

Figure 2. Switching Waveforms

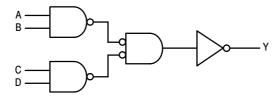


Figure 4. Expanded Logic Diagram (1/2 of the Device)

#### **ORDERING INFORMATION**

| Device          | Package              | Shipping <sup>†</sup> |
|-----------------|----------------------|-----------------------|
| MC74HCT20ADG    | SOIC-14<br>(Pb-Free) | 55 Units/Rail         |
| MC74HCT20ADR2G  | SOIC-14<br>(Pb-Free) | 2500/Tape & Reel      |
| MC74HCT20ADTR2G | TSSOP-14*            |                       |

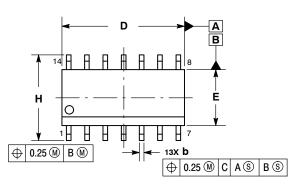
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*This package is inherently Pb-Free.

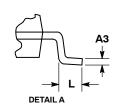


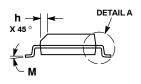


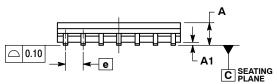
SOIC-14 NB CASE 751A-03 ISSUE L

**DATE 03 FEB 2016** 









## GENERIC MARKING DIAGRAM\*

MIN MAX

0.050 BSC

0.068

0.019

0.054

0.25 0.004 0.010

0.25 0.008 0.010

0.50 0.010 0.019

1.25 0.016 0.049

0.49 0.014

8.55 8.75 0.337 0.344 3.80 4.00 0.150 0.157

NOTES:
1. DIMENSIONING AND TOLERANCING PER

5. MAXIMUM MOLD PROTRUSION 0.15 PER

MILLIMETERS MIN MAX

1.27 BSC

0.19

0.25

0.40

SIDE

Α

A1 0.10

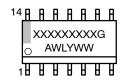
АЗ

**b** 0.35

D 8.55 E 3.80

e H h

ASME Y14.5M, 1994.
CONTROLLING DIMENSION: MILLIMETERS.
DIMENSION b DOES NOT INCLUDE DAMBAR
PROTRUSION. ALLOWABLE PROTRUSION
SHALL BE 0.13 TOTAL IN EXCESS OF AT
MAXIMUM MATERIAL CONDITION.
DIMENSIONS D AND E DO NOT INCLUDE
MOLD PROTRUSIONS.



XXXXX = Specific Device Code A = Assembly Location

WL = Wafer Lot
 Y = Year
 WW = Work Week
 G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

## 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIMENSIONS: MILLIMETERS

#### **STYLES ON PAGE 2**

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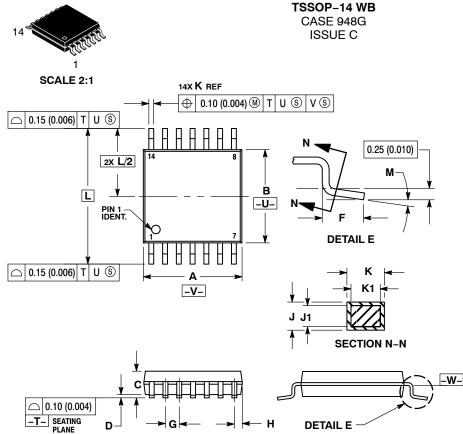
#### SOIC-14 CASE 751A-03 ISSUE L

#### DATE 03 FEB 2016

| STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE | STYLE 2:<br>CANCELLED   | STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE  | STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE  |
|---|---|---|---|
| STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE | STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE | STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE | STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE |

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**DATE 17 FEB 2016** 

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

|     | MILLIN | IETERS | INC   | HES   |
|-----|--------|--------|-------|-------|
| DIM | MIN    | MAX    | MIN   | MAX   |
| Α   | 4.90   | 5.10   | 0.193 | 0.200 |
| В   | 4.30   | 4.50   | 0.169 | 0.177 |
| С   |        | 1.20   |       | 0.047 |
| D   | 0.05   | 0.15   | 0.002 | 0.006 |
| F   | 0.50   | 0.75   | 0.020 | 0.030 |
| G   | 0.65   | BSC    | 0.026 | BSC   |
| Н   | 0.50   | 0.60   | 0.020 | 0.024 |
| J   | 0.09   | 0.20   | 0.004 | 0.008 |
| J1  | 0.09   | 0.16   | 0.004 | 0.006 |
| K   | 0.19   | 0.30   | 0.007 | 0.012 |
| K1  | 0.19   | 0.25   | 0.007 | 0.010 |
| L   | 6.40   | BSC    | 0.252 | BSC   |
| М   | o°     | 8 °    | 0 °   | 8 °   |

#### **GENERIC MARKING DIAGRAM\***



= Assembly Location

= Wafer Lot V = Year

W = Work Week

= Pb-Free Package (Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

| SOLDERIN    | G FOOTPRINT             |
|-------------|-------------------------|
| -           | 7.06                    |
| 1           |                         |
|             |                         |
| — <u>—</u>  |                         |
| , <u></u>   | PITCH                   |
| 14X<br>0.36 | <del></del>             |
| 1.26        | DIMENSIONS: MILLIMETERS |

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